1N4148W-BL

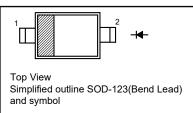
Silicon Epitaxial Planar Switching Diode

Features

Fast switching

PINNING

PIN	DESCRIPTION			
1	Cathode			
2	Anode			



Absolute Maximum Ratings (T_a = 25°C)

Parameter	Symbol	Value	Unit	
Peak Reverse Voltage	V_{RM}	100	V	
Reverse Voltage	V_R	75	V	
Average Rectified Forward Current	$I_{F(AV)}$	200	mA	
Non-repetitive Peak Forward Surge Current	at t = 1 s at t = 1 ms at t = 1 µs	I _{FSM}	0.5 1 4	А
Power Dissipation		P_{D}	400	mW
Operating Junction Temperature Range		T _j	- 65 to + 150	$^{\circ}$
Storage Temperature Range		T_{stg}	- 65 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit	
Thermal Resistance from Junction to Ambient 1)	$R_{ heta JA}$	312	°C/W	

¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



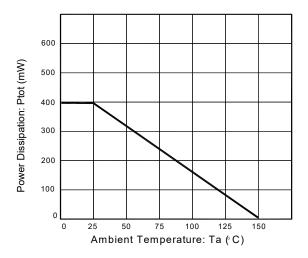
1N4148W-BL

Characteristics at T_a = 25℃

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I _R = 1 µA	$V_{(BR)R}$	75	-	V
Forward Voltage at $I_F = 1 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 150 \text{ mA}$	V _F	- - -	0.715 0.855 1 1.25	V
Peak Reverse Current at $V_R = 75 \text{ V}$ at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}$, $T_J = 150 ^{\circ}\text{C}$ at $V_R = 25 \text{ V}$, $T_J = 150 ^{\circ}\text{C}$	I _R		1 25 50 30	μΑ nA μΑ μΑ
Total Capacitance at $V_R = 0 V$, $f = 1 MHz$	C _T	-	2	pF
Reverse Recovery Time at $I_F = 10 \text{ mA}$, $I_{rr} = 0.1 \times I_R$, $V_R = 6 \text{ V}$, $R_L = 100 \Omega$	t _{rr}	-	4	ns

Electrical Characteristics Curves

Fig 1. Power Dissipation vs Ambient Temperature



Tj=25°C ________f=1MHZ

Fig 2. Total Capacitance vs. Reverse Voltage

0.7

0.6

0.5

0.4

0.3

0.2

0.1

0

C_T, Total Capacitance (pF)

V_R, Reverse Voltage (V)

Fig 3. Reverse Current vs. Reverse Voltage

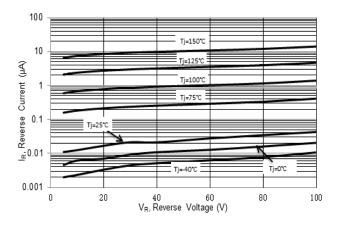
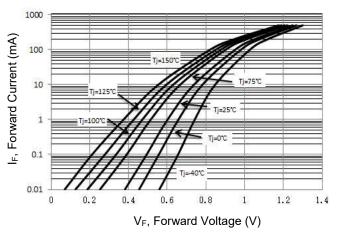


Fig 4. Forward Characteristics

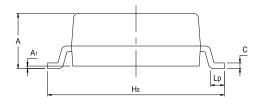
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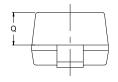


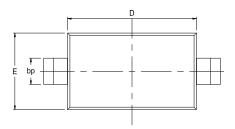
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123(Bend Lead)

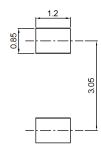






UNIT	Α	A_1	bp	С	D	E	H _E	Lp	Q
m. m.	1.21	0.1	0.7	0.14	2.7	1.7	3.8	0.4	0.65
mm	0.91	0	0.5	0.08	2.54	1.5	3.5	0.2	0.55

Recommended Soldering Footprint



Packing information

Package	Tape Width	Pitch		Reel	Size	Per Reel Packing Quantity	
Package	Package (mm)		(inch)	mm	(inch)	rei Reel Fackling Qualitity	
SOD-123BL	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000	

Marking information

"W1" = Part No.

" III " = Cathode line

Font type: Arial



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